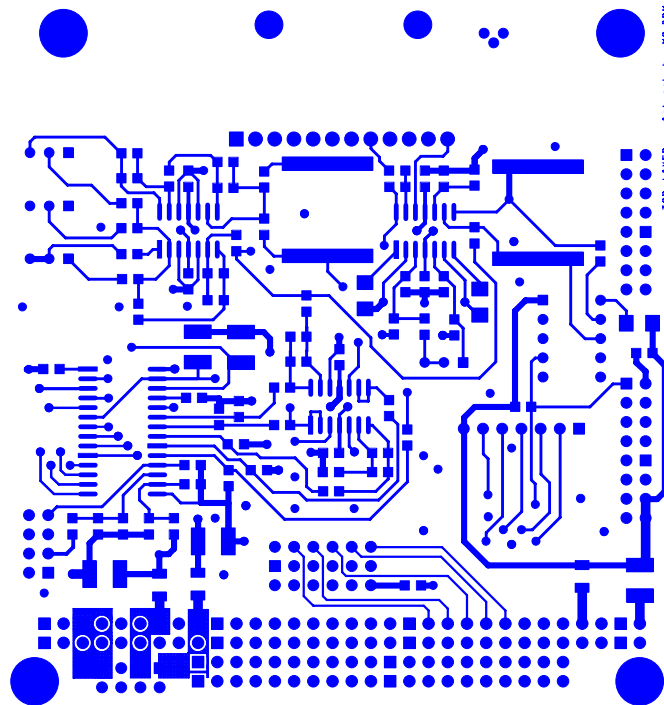
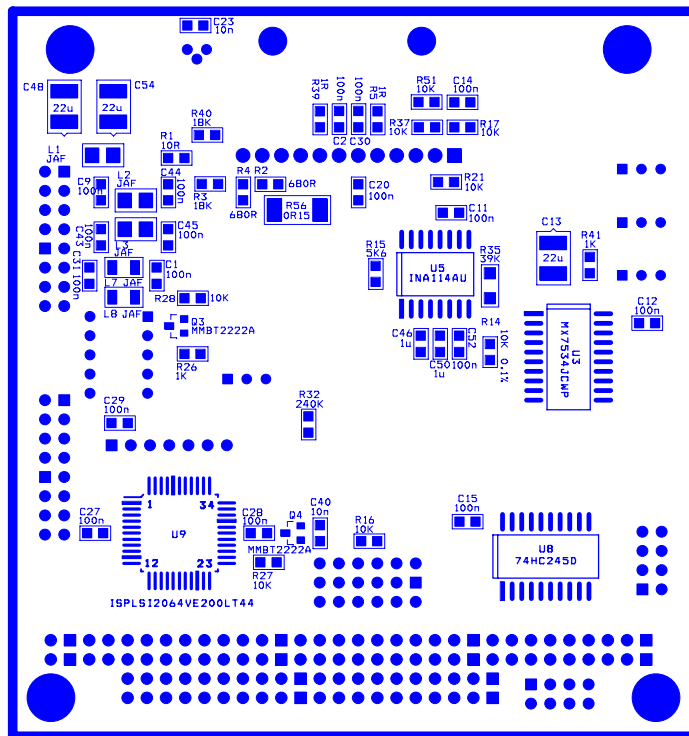


TOP LAYER - COMPONENT SIDE

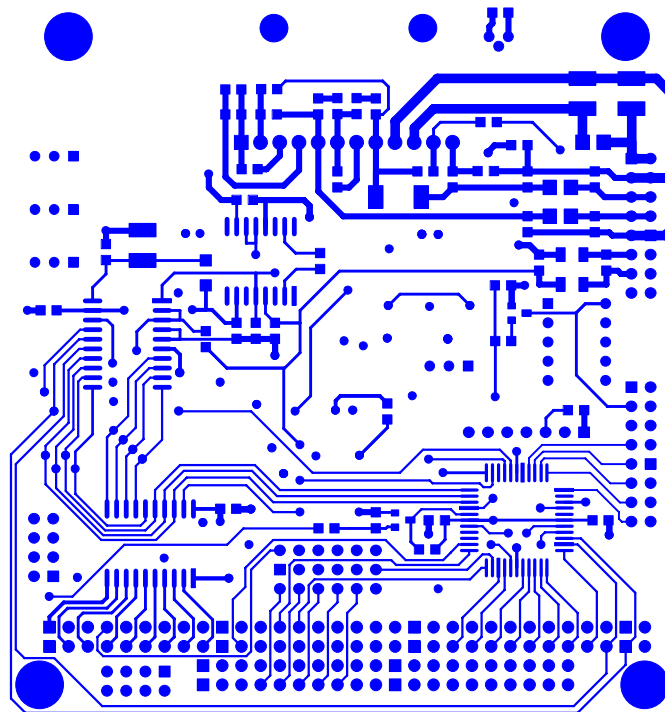


TOP LAYER - ATTACH BY MB.DPM

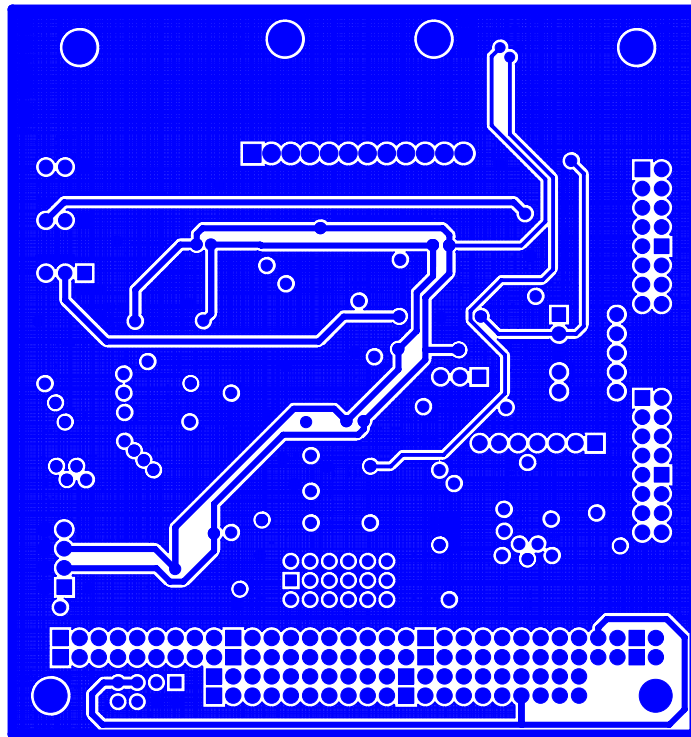




BOTTOM LAYER - SOLDER SIDE



INNER LAYER 1 - ANALOG GROUND



INNER LAYER 2 - DIGITAL GROUND

